# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating		
T <sub>STG</sub>	Storage Temperature	−65°C to +150°C		
T <sub>A</sub>	Ambient Temperature Under Bias	–55°C to +125°C		
TJ	Junction Temperature Under Bias	–55°C to +150°C		
V <sub>CC</sub>	V <sub>CC</sub> Pin Potential to Ground Pin	-0.5V to +7.0V		
V <sub>IN</sub>	Input Voltage <sup>(1)</sup>	-0.5V to +7.0V		
I <sub>IN</sub>	Input Current <sup>(1)</sup>	-30mA to +5.0mA		
Vo	Voltage Applied to Output in HIGH State (with V <sub>CC</sub> = 0V)			
	Standard Output	–0.5V to V <sub>CC</sub>		
	3-STATE Output	–0.5V to 5.5V		
	Current Applied to Output in LOW State (Max.)	twice the rated I <sub>OL</sub> (mA)		

## Note:

1. Either voltage limit or current limit is sufficient to protect inputs.

## **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating		
T <sub>A</sub>	Free Air Ambient Temperature	0°C to +70°C		
V <sub>CC</sub>	Supply Voltage	+4.5V to +5.5V		

# **DC Electrical Characteristics**

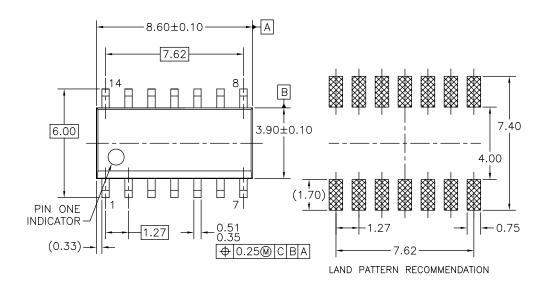
Symbol	Parameter		V <sub>CC</sub>	Conditions	Min.	Тур.	Max.	Units
$V_{IH}$	Input HIGH Voltage			Recognized as a HIGH Signal	2.0			V
V <sub>IL</sub>	Input LOW Voltage			Recognized as a LOW Signal			0.8	V
V <sub>CD</sub>	Input Clamp Diode Voltage		Min.	$I_{IN} = -18mA$			-1.2	V
V <sub>OH</sub>	Output HIGH Voltage	10% V <sub>CC</sub>	Min.	$I_{OH} = -1mA$	2.5			V
		5% V <sub>CC</sub>		$I_{OH} = -1mA$	2.7			
V <sub>OL</sub>	Output LOW Voltage 10% V <sub>CC</sub>		Min.	I <sub>OL</sub> = 20mA			0.5	V
I <sub>IH</sub>	Input HIGH Current		Max.	V <sub>IN</sub> = 2.7V			5.0	μA
I <sub>BVI</sub>	Input HIGH Current Breakdown Test		Max.	V <sub>IN</sub> = 7.0V			7.0	μA
I <sub>CEX</sub>	Output HIGH Leakage Current		Max.	$V_{OUT} = V_{CC}$			50	μΑ
$V_{ID}$	Input Leakage Test		0.0	$I_{ID} = 1.9 \mu A$ , All other pins grounded	4.75			V
I <sub>OD</sub>	Output Leakage Circuit Current		0.0	V <sub>IOD</sub> = 150mV, All other pins grounded			3.75	μA
I <sub>IL</sub>	Input LOW Current		Max.	V <sub>IN</sub> = 0.5V			-0.6	mA
Ios	Output Short-Circuit Current		Max.	V <sub>OUT</sub> = 0V	-60		-150	mA
I <sub>CCH</sub>	Power Supply Current		Max.	V <sub>O</sub> = HIGH		1.4	2.1	mA
I <sub>CCL</sub>	Power Supply Current		Max.	$V_O = LOW$		5.1	7.7	mA

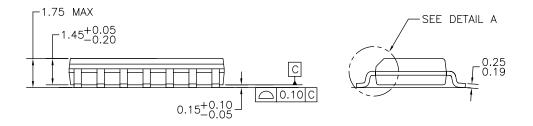
# **AC Electrical Characteristics**

		$\begin{aligned} & \textbf{T}_{\textbf{A}} = \textbf{+25}^{\circ}\textbf{C}, \\ & \textbf{V}_{\textbf{CC}} = \textbf{+5.0V}, \\ & \textbf{C}_{\textbf{L}} = \textbf{50}\textbf{pF} \end{aligned}$			$T_A = -55^{\circ}\text{C to } +125^{\circ}\text{C},$ $V_{CC} = +5.0\text{V},$ $C_L = 50 \text{ pF}$		$\begin{aligned} T_{A} &= 0 ^{\circ}\text{C to +70}^{\circ}\text{C}, \\ V_{CC} &= +5.0\text{V}, \\ C_{L} &= 50 \text{pF} \end{aligned}$		
Symbol	Parameter	Min.	Тур.	Max.	Min.	Max.	Min.	Max.	Units
t <sub>PLH</sub>	Propagation Delay,	2.4	3.7	5.0	2.0	7.0	2.4	6.0	ns
t <sub>PHL</sub>	$A_n$ , $B_n$ , $C_n$ to $O_n$	1.5	3.2	4.3	1.5	6.5	1.5	5.3	

# **Physical Dimensions**

Dimensions are in millimeters unless otherwise noted.





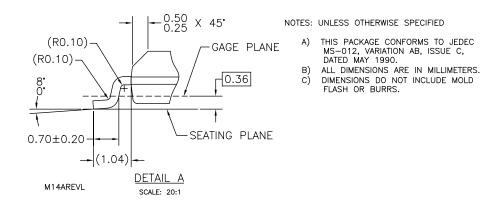
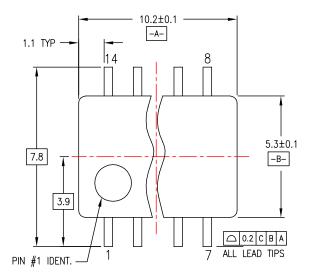
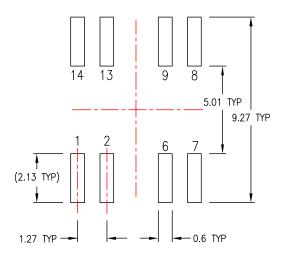


Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow Package Number M14A

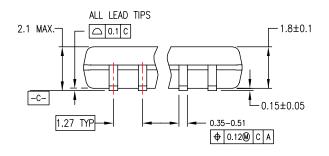
# Physical Dimensions (Continued)

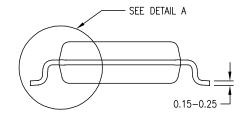
Dimensions are in millimeters unless otherwise noted.





## LAND PATTERN RECOMMENDATION



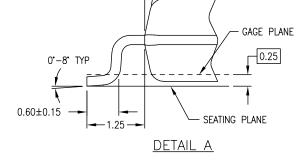


7° TYP

## DIMENSIONS ARE IN MILLIMETERS

## NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
  B. DIMENSIONS ARE IN MILLIMETERS.
  C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.



M14DREVC

Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M14D





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